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Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM)

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

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**Semiconductor devices - Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing -  
Human body model (HBM)  
(IEC 60749-26:2025)**

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 26: Essai de sensibilité  
aux décharges électrostatiques (DES) - Modèle du corps  
humain (HBM)  
(IEC 60749-26:2025)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 26: Prüfung der Empfindlichkeit gegen  
elektrostatische Entladungen (ESD) - Human Body Model  
(HBM)  
(IEC 60749-26:2025)

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**EN IEC 60749-26:2026 (E)****European foreword**

The text of document 47/2963/FDIS, future edition 5 of IEC 60749-26, prepared by TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-26:2026.

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IEC 60749-26 NOTE Approved as EN IEC 60749-26

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IEC 60749-26

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# INTERNATIONAL STANDARD

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**Semiconductor devices - Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model  
(HBM)**

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**Semiconductor devices -  
Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing -  
Human body model (HBM)**

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This edition includes the following significant technical changes with respect to the previous edition:

- a) new definitions have been added;
- b) text has been added to clarify the designation of and allowances resulting from “low parasitics”. The new designation includes the maximum number of pins of a device that can pass the test procedure.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2963/FDIS	47/2984/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices - Mechanical and climatic test methods*, can be found on the IEC website.

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## 1 Scope

This part of IEC 60749 establishes the procedure for testing, evaluating, and classifying components and microcircuits in accordance with their susceptibility (sensitivity) to damage or degradation by exposure to a defined human body model (HBM) electrostatic discharge (ESD).

The purpose of this document is to establish a test method that will replicate HBM failures and provide reliable, repeatable HBM ESD test results from tester to tester, regardless of component type. Repeatable data will allow accurate classifications and comparisons of HBM ESD sensitivity levels.

ESD testing of semiconductor devices is selected from this test method, the machine model (MM) test method (see IEC 60749-27) or other ESD test methods in the IEC 60749 series. Unless otherwise specified, this test method is the one selected.

## 2 Normative references

There are no normative references in this document.

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